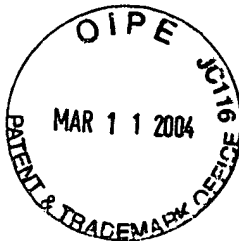


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of :

Rongxiang Hu
Philippe Schoenborn
Masaichi Eda



Serial No. :

09/928,570

Group Art Unit :

1765

Filed :

August 13, 2001

Examiner :

Umez Eronini, L.

For :

High Selectivity SiC Etch In
Integrated Circuit Fabrication

Atty Docket :

100.399 / 01-099

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P. O. Box 1450, Alexandria, VA 22313-1450, on the date below:

Connie Del Castillo

3/11/04

Connie Del Castillo

Date

Signature

SUBMISSION OF FORMAL DRAWINGS PURSUANT TO 37 C.F.R. §1.85

Official Draftsman

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant hereby substitutes the enclosed formal drawings for those presently in the above referenced application.

LSI Logic Corporation
1551 McCarthy Blvd., MS D-106
Milipitas, CA 95035
408-433-7475

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Timothy Croll".

Timothy Croll

Reg. No. 36,771

Date: 10 MAR 04